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**Flexible Epoxy**

**2-Component**

Available in **Premixed Frozen**

Available in **"Bipak" Meter-Mix**

**Syringes**

**IDEAL FOR:**

- Bonding Large Area Device
- Bonding Adherends with CTE Mismatches
- Substrate Attach
- Component Attach

**DESCRIPTION:**

EG7650/EG7659 is reworkable, unfilled, electrically insulating epoxy paste adhesive which exhibits outstanding flexibility for bonding materials with highly mismatched CTE's (i.e., alumina to aluminum, silicon to copper). This thixotropic paste has a pot-life of about four hours at 25°C.

It can be readily reworked at 80-100°C.

**AVAILABILITY:**

EG7650/EG7659 is available in syringes for automatic needle dispense applications or in jars. Both viscosity and thixotropic index can be modified to your specific needs. The material can be shipped premixed and frozen upon request. If shipped premixed and frozen store at -40°C for a shelf life of up to three months, after mixing.

**APPLICATION PROCEDURES:**

- ( 1 ) Store Part A & Part B at ambient.
- ( 2 ) Mix A & B 1:1 by weight.
- ( 3 ) Cure according to one of the recommended schedules.

**CAUTION:** This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details.

The information contained herein is believed to be reliable. All recommendations or suggestions are made without guarantee inasmuch as conditions and methods of commercial use are beyond our control. Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is to be used in manufacturing and in the final product. Under no circumstance shall AI Technology be liable for accidental, consequential or other damages arising from the use or handling of this product.

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**PRIMA-BOND**  
**EG7650/EG7659**

**TYPICAL PROPERTIES\***

Electrical Resistivity ( 150 °C/ 60 minutes )	>1x10 <sup>14</sup> ohm-cm
Dielectric Strength (Volts/mil)	> 750
Glass Transition Temp.(°C)	-25 ±10%
Current Carrying Capabilities	N/A
Lap-Shear Strength	<b>&gt;1000 psi</b>
	>6.9 N/mm <sup>2</sup>
Device Push-off Strength	<b>&gt;1800 psi</b>
	>12.4 N/mm <sup>2</sup>
Cured Density (gm/cc)	1.2 ±10%
Thermal Conductivity	40 Btu-in/hr-ft <sup>2</sup> -°F ±10%
	<b>5.7 W/m-°C ±10%</b>
Linear Thermal Expansion Coeff. (ppm/°C)	N/A
Maximum Continuous Operation Temp. (°C)	<150
Avg. Viscosity(0.5 rpm, 24°C) (Brookfield DV-1, spindle CP51)	<b>60,000 cp ±20%</b>

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**CURE SCHEDULES:**

Temperature	Time
85°C	<b>4 hr</b>
150°C	30 min

If the material is premixed and frozen thaw for 30 minutes, apply and cure according to one of the recommended schedules.

\*\*Shelf life is for unmixed components. If premixed: -40°C for three months .  
**Pot life is about four hour at 25°C,** after mixing.

**SHELF LIFE:**

Storage temperature	Shelf Life
**25°C	6 mo